Texas Instruments

Reliability Estimator

	Early life failure rate	MTBF / FIT		Early life failure rate supporting data				MTBF / FIT supporting data						
Part number	**ELFR-DPPM**	**MTBF**	**FIT**	**Conf level (%)**	**Test temp (°C)**	**Sample size**	**Fails**	**Usage temp (°C)**	**Conf level (%)**	**Activation energy (eV)**	**Test temp (°C)**	**Test duration (hours)**	**Sample size**	**Fails**
TPS51200DRCR	6	1x 10^{10}	0.1	60	125	150108	0	55	60.0	0.7	125	1000	159230	0

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